

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Withdrawn-Currently Amended) A method of forming a patterned ~~thin~~ film including a linear portion by frame plating, the method comprising:

~~the step of forming a frame having an undercut near a bottom thereof on a base layer; and~~

~~the plating step of forming the patterned thin film by plating through the use of the frame such that the linear portion has a first portion and a second portion, wherein the a second portion ~~else~~is closer to the base layer than the first portion, and wherein the second portion touches the base layer and has~~having a width greater than a width of the ~~remaining first portion of the linear portion.~~

2. (Withdrawn-Currently Amended) The method according to claim 1, wherein the patterned ~~thin~~ film is formed to include a plurality of linear portions disposed side by side.

3. (Currently Amended) A patterned ~~thin~~ film disposed on a base layer and including a linear portion, wherein the linear portion has a first portion and a second portion, wherein the a second portion ~~else~~is closer to the base layer than the first portion, and wherein the second portion touches the base layer, the second portion having a width greater than a width of the ~~remaining first portion of the linear portion.~~

4. (Currently Amended) The patterned ~~thin~~ film according to claim 3, including a plurality of linear portions disposed side by side.